N-Channel 60V, 1.7Ω Typ. Power MOSFET

Description

Features

• 60V, 0.2A

$$R_{DS(ON)}$$
 Typ = 1.7 Ω @ V_{GS} = 10 V

$$R_{DS(ON)}$$
 Typ = 2.0 Ω @ V_{GS} = 4.5 V

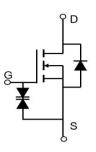
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free
- ESD Protected: 2KV

Application

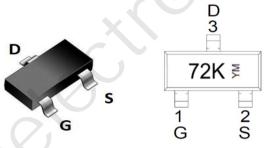
- Battery Operated Systems
- Direct logic-level Interface:

TTL/CMOS

Solid-State Relays







Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMLATL2N7002K	72K	SOT-323-3L	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ $T_J = 25$ °C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		60	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _A = 25°C	0.2	А
I _D	Continuous Drain Current	T _A = 100°C	0.12	А
I _{DM}	Pulsed Drain Current (1)		0.8	А
P_{D}	Power Dissipation	T _A = 25°C	0.3	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾		415	°C/W
T_J,T_STG	Junction & Storage Temperature R	ange	-55 to 150	°C



N-Channel 60V, 1.7Ω Typ. Power MOSFET

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Char	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±10	μА
On Char	acteristics				<u>C</u>	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.6	2	V
Б		$V_{GS} = 10V, I_D = 0.2A$	-	1.7	2.1	Ω
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 4.5V, I_D = 0.1A$	-	2	2.4	Ω
Dynamic	Characteristics					
C_{iss}	Input Capacitance		-	28	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 25V$, f = 1MHz	X -	11	-	pF
C_{rss}	Reverse Transfer Capacitance	1 1141112		4	-	pF
Q_g	Total Gate Charge	. 0	9 -	2	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0$ to 4.5V $V_{DS} = 10V$, $I_{D} = 0.2A$	-	0.3	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	0.6	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime	.()	-	2	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 10V$	-	15	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_{D} = 0.2A, R_{GEN} = 10 Ω	-	7	-	ns
t_f	Turn-Off Fall Time		-	20	-	ns
Drain-So	urce Diode Characteristics and I	Max Ratings				
I _S	Maximum Continuous Drain to Source D	liode Forward Current	-	-	0.2	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	0.8	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 0.2A$	_	_	1.2	V

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} R_{BJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

N-Channel 60V, 1.7Ω Typ. Power MOSFET

Test Circuit

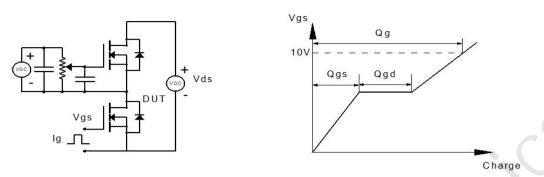


Figure 1: Gate Charge Test Circuit & Waveform

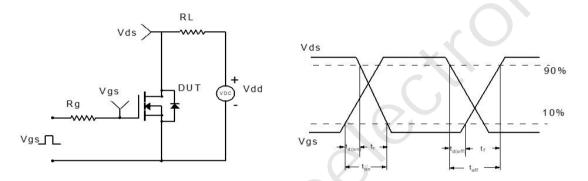


Figure 2: Resistive Switching Test Circuit & Waveform

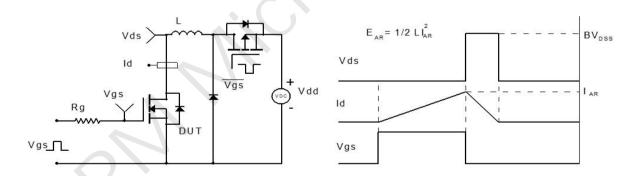


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

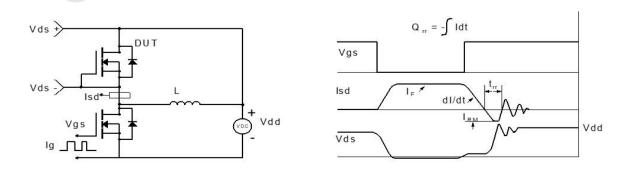
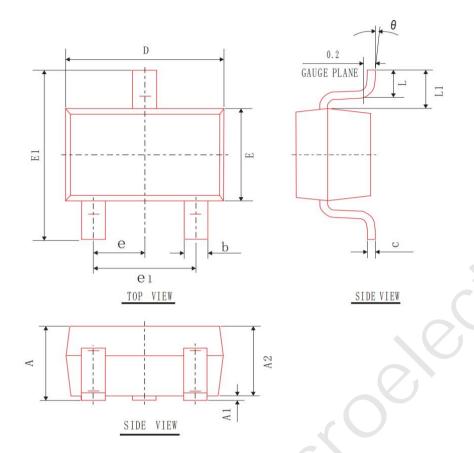


Figure 4: Diode Recovery Test Circuit & Waveform

N-Channel 60V, 1.7Ω Typ. Power MOSFET

Package Mechanical Data(SOT-323-3L)



SYMBOL	MIN	NOM	MAX	
A	0.90	1.00	1.10	
A1	0.00	0.05	0.10	
A 2	0.90	0.95	1.00	
b	0.20	0.25	0.30	
C	0.08	0.10	0.15	
e ₁	1.20	1.30	1.40	
D	2.00	2.10	2. 20	
Е	1. 15	1. 25	1.35	
E1	2.15	2.30	2.45	
L	0. 26	0.36	0.46	
θ	0°	4°	8°	
L1	0.525 REF			
e	0.65 TYP			

COMMON DIMENSIONS

Important Notice

The information presented in datasheets is for reference only. CRM reserves the right to make changes at any time to any products or information herein, without notice.

Customers are responsible for the design and applications, including compliance with all laws, regulations and safety requirements or standards.

"Typical" parameters which provided in datasheets can vary in different applications and actual performance may vary over time. Customers are responsible for doing all necessary testing to minimize the risks associated with their applications and products.

is a registered trademark of Wuxi CRM Microelectronics Co. , Ltd. Copyright ©2023 CRM Microelectronics Co. , Ltd. All rights reserved.

Contact information

For more information, please visit: http://www.crm-semi.tech For sales information, please send an email to: sales@crm-semi.com